## 2SD2321

## Silicon NPN epitaxial planar type

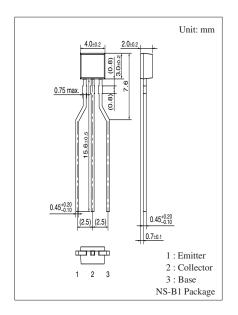
#### For low-frequency power amplification

#### ■ Features

- ullet Low collector-emitter saturation voltage  $V_{\text{CE(sat)}}$
- Satisfactory operation performances at high efficiency with the low-voltage power supply

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	40	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	20	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	7	V	
Collector current	$I_C$	5	A	
Peak collector current	$I_{CP}$	8	A	
Collector power dissipation	P <sub>C</sub>	400	mW	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	$T_{stg}$	-55 to +150	°C	



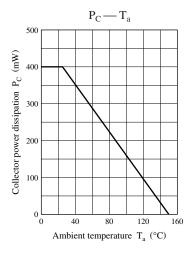
### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

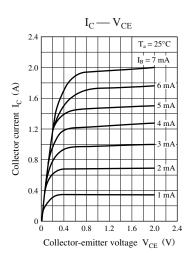
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_C = 1 \text{ mA}, I_B = 0$	20			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \ \mu A, \ I_C = 0$	7			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 10 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CB} = 10 \text{ V}, I_{B} = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 7 \text{ V}, I_{C} = 0$			0.1	μΑ
Forward current transfer ratio	h <sub>FE1</sub> *	$V_{CE} = 2 \text{ V}, I_{C} = 0.5 \text{ A}$	230		600	_
	h <sub>FE2</sub>	$V_{CE} = 2 \text{ V}, I_{C} = 2 \text{ A}$	150			
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 3 \text{ A}, I_B = 0.1 \text{ A}$		0.28	1.00	V
Transition frequency	$f_T$	$V_{CB} = 6 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance	C <sub>ob</sub>	$V_{CB} = 20 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		26	50	pF
(Common base, input open circuited)						

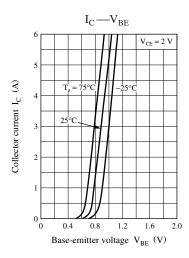
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

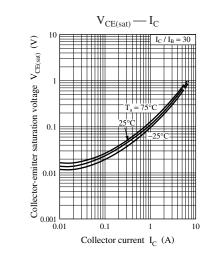
#### 2. \*: Rank classification

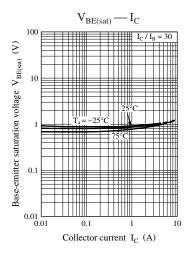
Rank	Q	R
h <sub>FE1</sub>	230 to 380	340 to 600

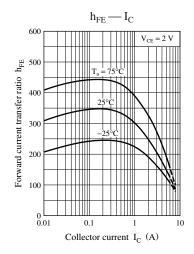


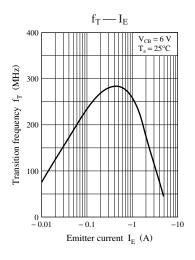


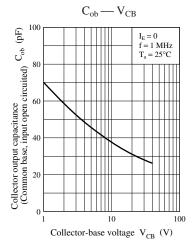


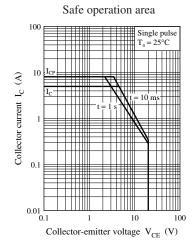












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